



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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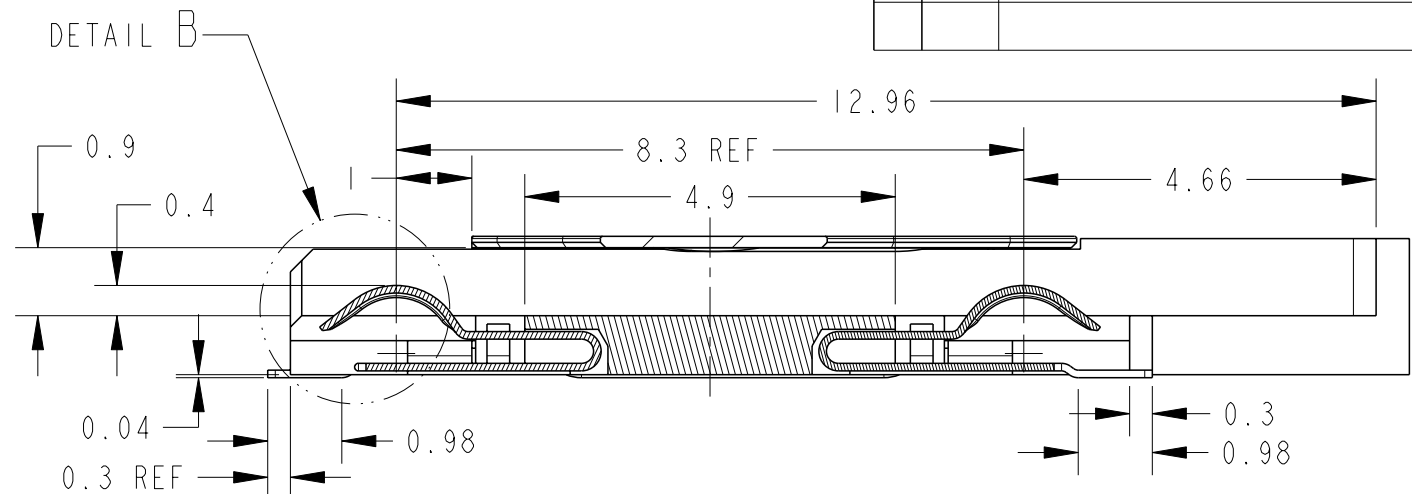
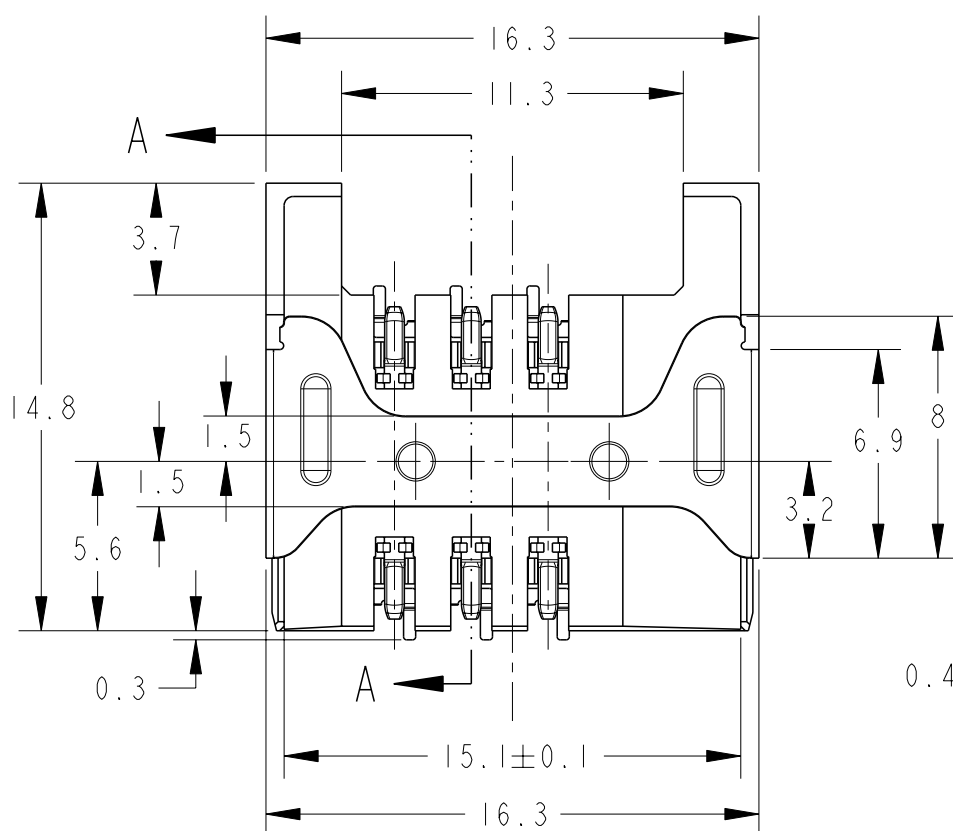
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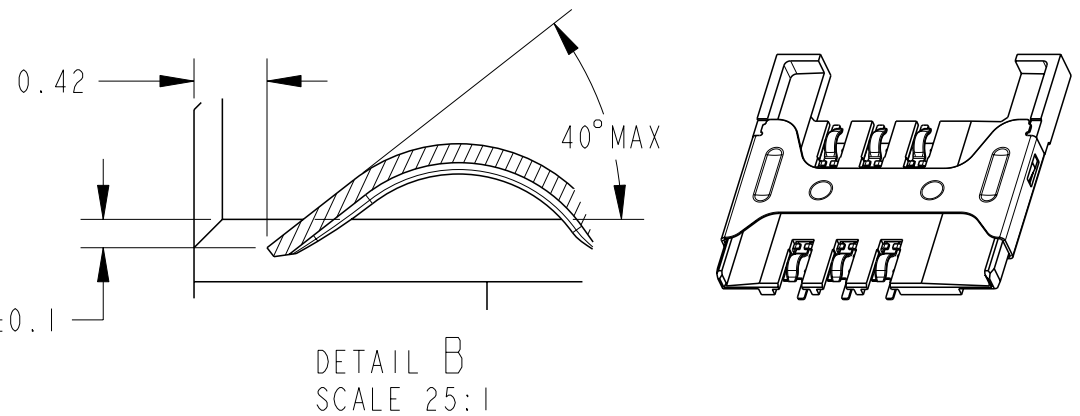


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| LOC | DIST | REVISIONS<br>変更              |           |     |      |
|-----|------|------------------------------|-----------|-----|------|
| P   | LTR  | DESCRIPTION                  | DATE      | DWN | APVD |
| J   | -    | REVISED AS PER ECR-12-016199 | 13SEP2012 | C.O | K.K  |

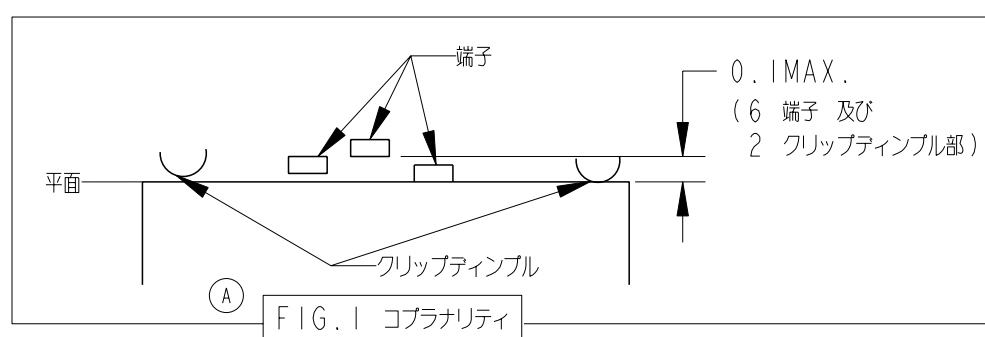
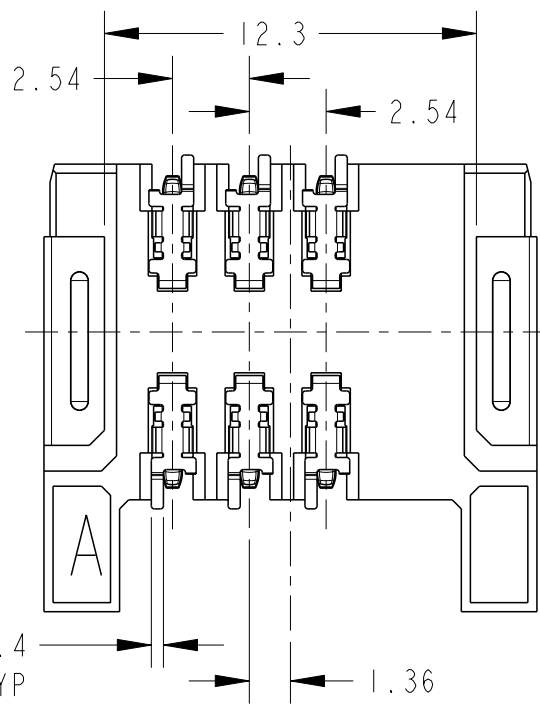
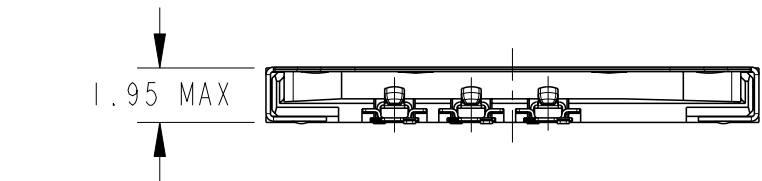


- | ; 本図  
 - | ; AS SHOWN  
 SECT A-A  
 SCALE 10:1



- CONTACT: 材料 銅合金  
 めっき 全面Ni下地: 1.27μm以上  
 接点部PdNi: 1.0μm以上 Au: 0.2μm以上  
 半田付け部Au: 0.05μm以上  
 クリップ: 材料 ステンレス  
 めっき 全面Ni下地: 1.3μm以上  
 スズ: 1μm以上  
 ハウジング: 熱可塑性樹脂
- 設計推奨半田厚みは100μm以上、推奨半田付け範囲は参考半田パターンに対し100%とする
- コプラナリティは0.1mm以下(FIG.1参照)

- CONTACT: COPPER ALLOY  
 ALL OVER Ni: 1.27μm MIN.  
 CONTACT AREA PdNi: 1.0μm MIN. Au: 0.2μm MIN.  
 SOLDERING AREA Au: 0.05μm MIN.
- CLIP: SUS  
 ALL OVER Ni: 1.3μm MIN.  
 Tin: 1μm MIN.  
 HOUSING: THERMOPLASTIC
- RECOMMENDED SOLDERING THICKNESS; 100μm MIN.  
 RECOMMENDED SOLDERING AREA;  
 100% OF REFERENCE LAYOUT PATTERN
- COPLANARITY; 0.1MAX. (SEE FIG.1)



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|                            |   |                |              |
|----------------------------|---|----------------|--------------|
| DIMENSIONS:<br>単位: 耗<br>mm | TOLERANCES UNLESS OTHERWISE SPECIFIED:<br>一般公差 ±0.15<br>0-PLC ±<br>1-PLC ±0.5<br>2-PLC ±0.13<br>3-PLC ±0.013<br>4-PLC ±0.0001<br>ANGLES ± | MATERIAL<br>材料 | FINISH<br>仕上 |
|----------------------------|---|----------------|--------------|

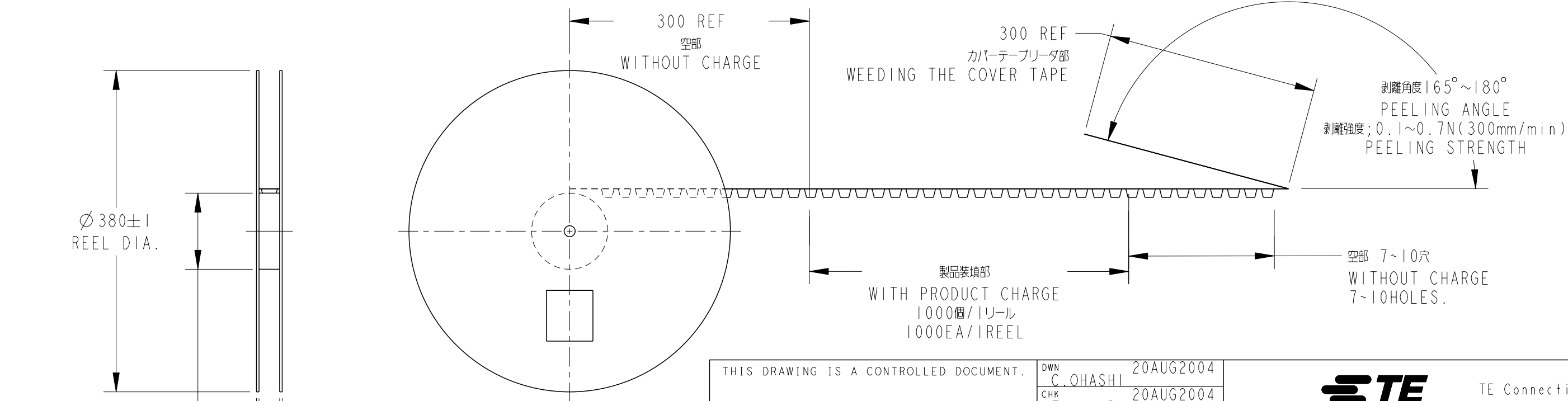
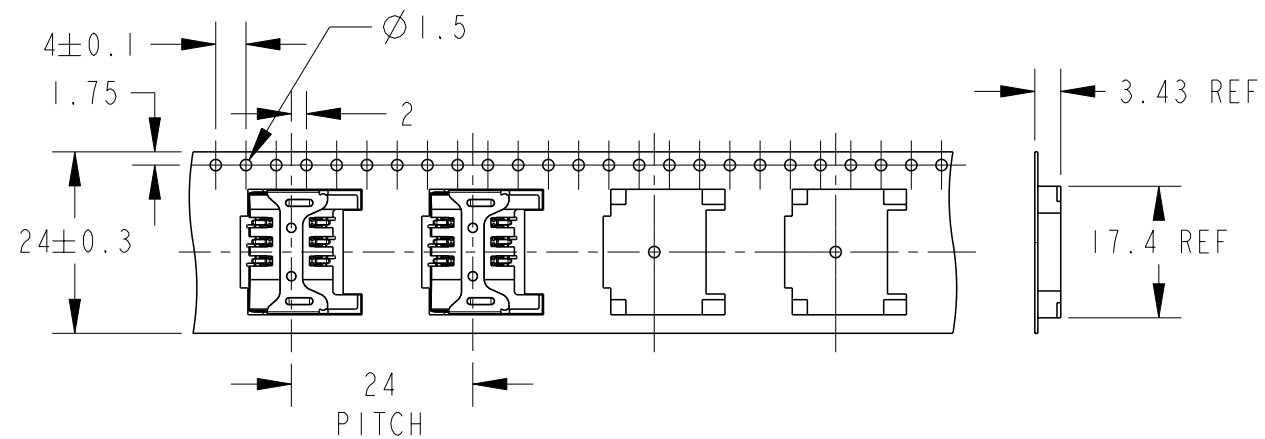
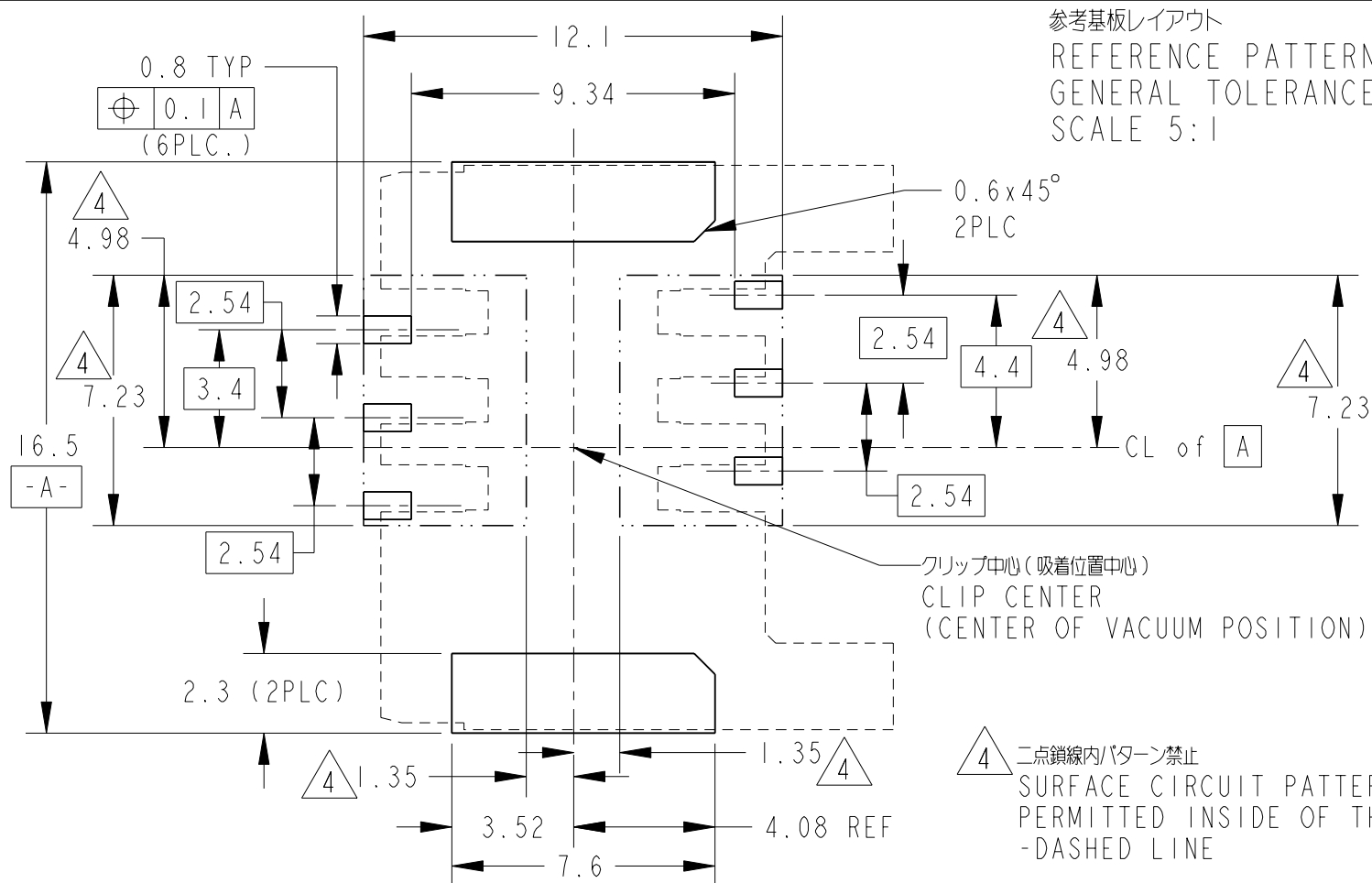
|                                  |                               |                                 |
|----------------------------------|-------------------------------|---------------------------------|
| DWN<br>C. OHASHI<br>20AUG2004    | CHK<br>T. KIMURA<br>20AUG2004 | APVD<br>K. IKEGAMI<br>20AUG2004 |
| PRODUCT SPEC<br>製品規格<br>108-5998 |                               |                                 |
| APPLICATION SPEC<br>取付適用規格       |                               |                                 |
| WEIGHT<br>(計算値) 0.36g            | CUSTOMER DRAWING              |                                 |

|                 |                    |                                   |               |
|-----------------|--------------------|-----------------------------------|---------------|
| TE Connectivity |                    | NAME<br>名称                        |               |
|                 |                    | SUPER LOW PROFILE<br>SIM<br>HI.95 |               |
| SIZE<br>A3      | CAGE CODE<br>00779 | DRAWING NO<br>C=1747314           | RESTRICTED TO |
| SCALE<br>尺度 4:1 |                    | SHEET<br>1 OF 2                   | REV<br>B1     |

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|-----|------|-----------|-----|-------------|------|-----|------|
|     |      | P         | LTR | DESCRIPTION | DATE | DWN | APVD |
| J   | -    |           | -   | SEE SHEET 1 | -    | -   | -    |

参考基板レイアウト  
 REFERENCE PATTERN LAYOUT  
 GENERAL TOLERANCE; ±0.05  
 SCALE 5:1



|   |  |                                 |   |                         |
|---|--|---------------------------------|---|-------------------------|
| THIS DRAWING IS A CONTROLLED DOCUMENT.  |  | DWN<br>C. OHASHI<br>20AUG2004   | TE Connectivity                           |                         |
| DIMENSIONS:<br>mm   |  | CHK<br>T. KIMURA<br>20AUG2004   |   |                         |
| TOLERANCES UNLESS OTHERWISE SPECIFIED:  |  | APVD<br>K. IKEGAMI<br>20AUG2004 | NAME<br>SUPER LOW PROFILE<br>SIM<br>HI.95 |                         |
| 0 PLC ±-<br>1 PLC ±0.5<br>2 PLC ±0.13<br>3 PLC ±0.013<br>4 PLC ±0.0001<br>ANGLES ±- |  | PRODUCT SPEC<br>108-5998        | SIZE<br>A3                                |                         |
| MATERIAL -  |  | APPLICATION SPEC<br>-           | CAGE CODE<br>00779                        | DRAWING NO<br>C-1747314 |
| FINISH -  |  | WEIGHT<br>0.36g                 | RESTRICTED TO<br>-                        |                         |
|   |  | CUSTOMER DRAWING                | SCALE<br>4:1                              | SHEET<br>2 OF 2         |
|   |  |                                 | REV<br>B1                                 |                         |